

Final Product/Process Change Notification Document #:FPCN25729XI Issue Date:16 Apr 2025

Title of Change:	Wafer Fab Site Addition of onsemi, Bucheon Korea as Alternate Fab Site for ESD and Surge Protection Products and Datasheet Update		
Proposed First Ship date:	23 Jul 2025 or earlier if approved by customer		
Contact Information:	Contact your local onsemi Sales Office		
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.		
Additional Reliability Data:	Contact your local onsemi Sales Office		
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com		
Marking of Parts/ Traceability of Change:	Changed material can be identified by lot code		
Change Category:	Wafer Fab Change		
Change Sub-Category(s):	Datasheet/Product Doc change, Manufacturing Site Addition		
Sites Affected:	•		
onsemi Sites		External Foundry/Subcon Sites	
onsemi Bucheon, Korea		None	

#### Description and Purpose:

This Final Product Change Notification (FPCN) is to inform customers about the dual source wafer fab strategy for the devices listed in the Affected Parts List.

Upon implementation of this FPCN, parts can be sourced from either LA Semiconductor or onsemi Bucheon, Korea.

	From		
Manufacturing location for Wafer Fab	LA Semiconductor, Idaho, United States	LA Semiconductor, Idaho, United States onsemi Bucheon, Korea	

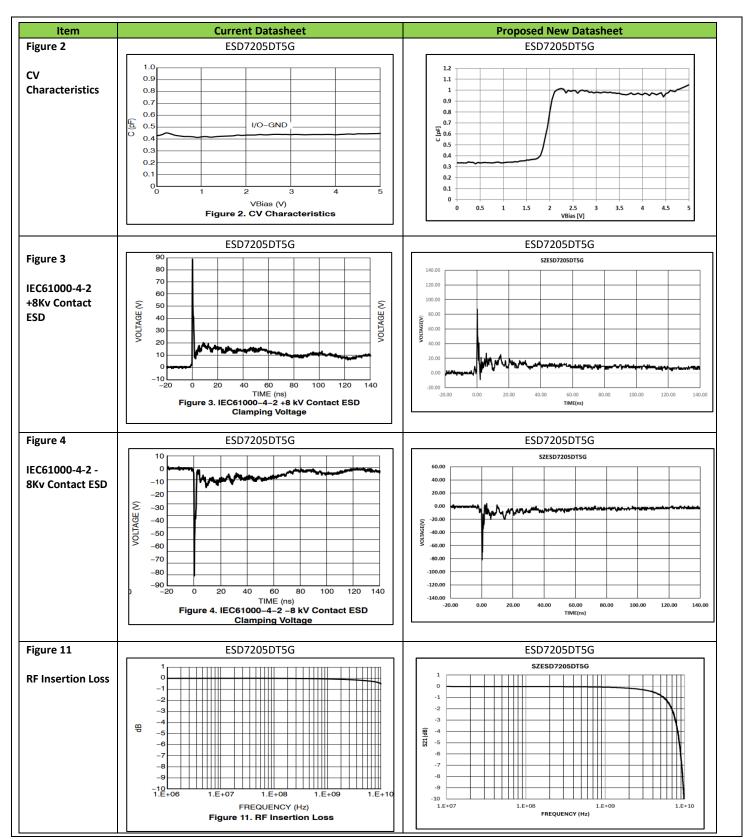
The datasheet for the affected part will be split for clarity.

The RF insertion loss, capacitance over frequency, and IEC61000–4–2 contact ESD clamping voltage graphs will also be updated to better represent ESD7205DT5G.

There is no product marking changes as a result of this change.

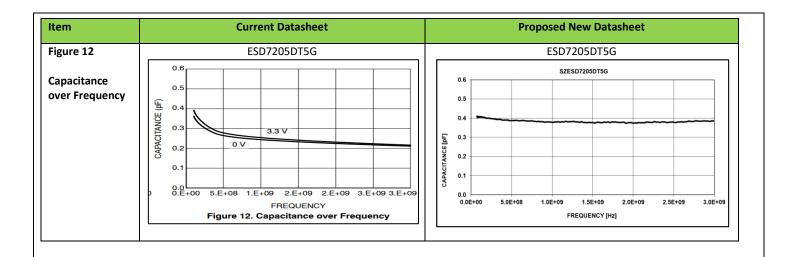


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# onsemi

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#### **Reliability Data Summary:**

#### QV DEVICE NAME: SZESD7205DT5G RMS: L97194, L100723 PACKAGE: SOT723

Test	Specification	Condition	Interval	Results
High Temperature Reverse Bias	JESD22-A108	Ta=150°C, 100% max rated V	1008 hrs	0/231
High Temperature Storage Life	JESD22-A103	Ta=150°C	1008 hrs	0/231
Preconditioning	J-STD-020 JESD-A113	MSL 1@260°C, TC, uHAST, HAST for surface mount pkgs only		0/693
Temperature Cycling	JESD22-A104	Ta= -55°C to +150°C	1000 cyc	0/231
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/231
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/ 231

#### **Electrical Characteristics Summary:**

Electrical characteristics are not impacted.

### List of Affected Parts:

**Note:** Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Part Number	Qualification Vehicle
ESD7205DT5G	SZESD7205DT5G